

REMARKS

Reconsideration of the above-identified application in view of the foregoing amendments and following remarks is respectfully requested.

A. Status of the Claims And Explanation Of Amendments

Claims 1-14 are pending. By this paper, claims 1 5 and 8 have been amended to clarify that, in claim 1 for example, “a periphery of the sealing layer has an angle of 30 to 60° with respect to a corresponding side of the circuit wiring substrate.” Support for these amendments is found throughout the application as originally filed including Figure 1A and its associated text. No new matter will be added to this application by entry of these amendments. Moreover, these amendments comply with 37 CFR § 1.116 as placing the claimed in better form for appeal Entry is requested.

Claim 1 was rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by U.S. Patent No. 6,177,724 to Sawai (“Sawai”). Claims 2, 4, 5-8 and 12-14 were rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Sawai in view of U.S. Patent No, 6,303,998 to Murayama (“Murayama”). Claims 4 and 9-11 were rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Sawai and Murayama and further in view of U.S. Patent No. 6,350,952 to Gaku et al. (“Gaku”).

B. Claims 1-14 Are Patentably Distinct From The Cited References

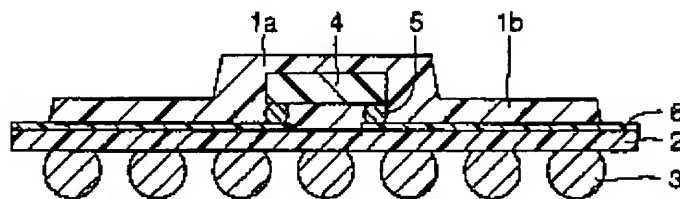
The rejections of claims 1-14 are respectfully traversed. As explained more fully below, the requirements for such rejections are not met. In particular, none of the cited references teaches, discloses or suggests a sealing layer as recited in the pending claims.

Applicants' independent claim 1 recites:

An area array semiconductor device comprising:
a circuit wiring substrate having a circuit wiring;
a semiconductor chip having a top face and a bottom face, the bottom face being mounted on the circuit wiring substrate and electrically connected with the circuit wiring; and
a sealing layer composed of a sealing resin positioned on the top face of the semiconductor chip;
wherein the sealing layer is formed such that a periphery of the sealing layer has an angle of 30 to 60° with respect to a corresponding side of the circuit wiring substrate.

The Office Actions alleges that Sawai's semiconductor device shows each of these features. As shown in Sawai's Figure 3 (reproduced below), there is a semiconductor chip (4) attached to a frame (2) via inner bumps (5) and wiring patterns (6) that is sealed with resin (1a, 1b):

FIG. 3



As shown in Sawai's Figure 5 (reproduced below), the chip (4) and sealing layer (1a and 1b) have sides that are roughly parallel to the frame (2):

Accordingly, as Applicants cannot find element “the sealing layer is formed such that a periphery of the sealing layer has an angle of 30 to 60° with respect to a corresponding side of the circuit wiring substrate” of claim 1 in any of the cited documents, at least independent

Appl. No. 10/686,885

Paper dated May 16, 2005

Reply to Office Action dated March 16, 2005

claims 1, 5 and 8, and their dependent claims 2-4, 6-7, 9-14 are respectfully asserted to be in condition for allowance.

Applicants have chosen in the interest of expediting prosecution of this patent applicant to distinguish the cited documents from the pending claims as set forth above. These statements should not be regarded in any way as admissions that the cited documents are, in fact, prior art. Finally, Applicants have not specifically addressed the rejections of the dependent claims. Applicants respectfully submit that the independent claims, from which they depend, are in condition for allowance as set forth above. Accordingly, the dependent claims also are in condition for allowance. Applicants, however, reserve the right to address such rejections of the dependent claims in the future as appropriate.

Appl. No. 10/686,885
Paper dated May 16, 2005
Reply to Office Action dated March 16, 2005

CONCLUSION

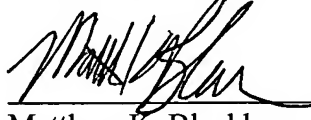
For the above-stated reasons, this application is respectfully asserted to be in condition for allowance. An early and favorable examination on the merits is requested. In the event that a telephone conference would facilitate the examination of this application in any way, the Examiner is invited to contact the undersigned at the number provided.

THE COMMISSIONER IS HEREBY AUTHORIZED TO CHARGE ANY ADDITIONAL FEES WHICH MAY BE REQUIRED FOR THE TIMELY CONSIDERATION OF THIS AMENDMENT UNDER 37 C.F.R. §§ 1.16 AND 1.17, OR CREDIT ANY OVERPAYMENT TO DEPOSIT ACCOUNT NO. 13-4500, ORDER NO. 1232-5176.

Respectfully submitted,
MORGAN & FINNEGAN, L.L.P.

Dated: May 16, 2005

By:



Matthew K. Blackburn
Registration No. 47,428

Correspondence Address:

MORGAN & FINNEGAN, L.L.P.
3 World Financial Center
New York, NY 10281-2101
(212) 415-8700 Telephone
(212) 415-8701 Facsimile